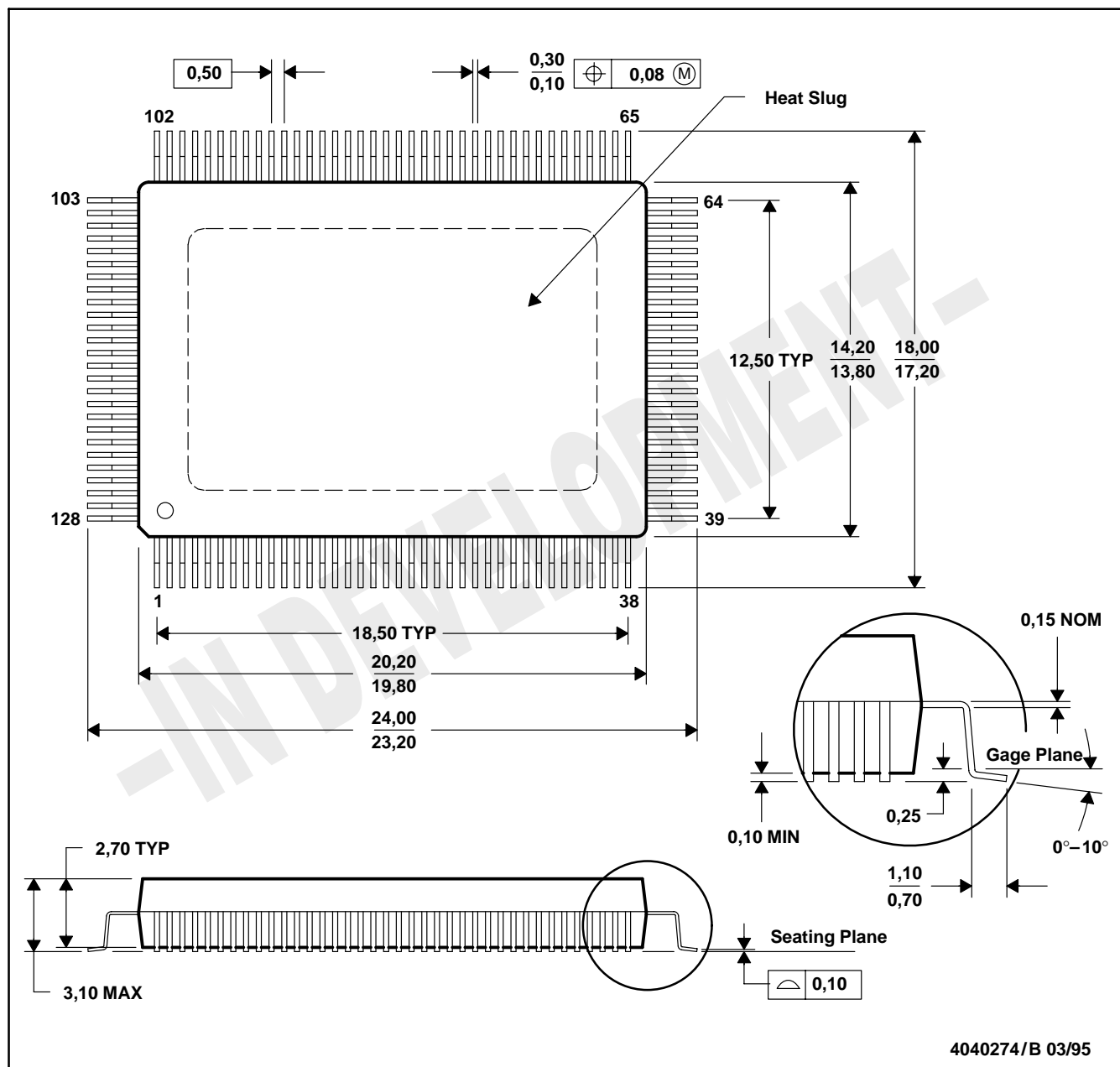


PAC (R-PQFP-G128)

PLASTIC QUAD FLATPACK (DIE-DOWN)



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Thermally enhanced molded plastic package (HSL) exposed on package bottom
 D. Contact field sales office to determine if a tighter coplanarity requirement is available for this package.

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